

# **iMAPS New England – 44<sup>th</sup> Symposium & Expo**

**The Largest Regional Symposium Dedicated to  
Microelectronics and Packaging**

**Holiday Inn – Boxborough Conference Center**

**Boxborough, Massachusetts**

**May 2, 2017**



**EarlyBird Exhibitor Registration is Open!!**

**The Technical Program is Being Assembled**

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The New England Chapter

## **Call for Papers & Posters**

- 2D-3D & Beyond
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- MEMS Sensors & Nano Technology
- Wearables - Consumer Applications
- Advanced Semiconductor Packaging
- Printed Electronics - Additive Manufacturing
- Nanoelectronic - Optoelectronic Packaging
- New & Emerging Materials-Technologies

**Symposium Technical Chair**

**Dr. Parshant Kumar, Draper**

**Please e-mail your 250 word abstract to:**

**[pkumarbos@gmail.com](mailto:pkumarbos@gmail.com)**

**phone 617-258-4417 skype: kparshant**

**Deadline for Submission – December 31, 2016**

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